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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Sadanori Kumazawa	11/05/2008
Hiroyuki Ohme	11/05/2008
Yuki Amano	11/11/2008
Takamasa Owaki	11/19/2008

RECEIVING PARTY DATA

Name:	Toray Industries, Inc.	
Street Address:	1-1, Nihonbashi-Muromachi 2-chome	
Internal Address:	Chuo-ku	
City:	Tokyo	
State/Country:	JAPAN	
Postal Code:	103-8666	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	12306761

CORRESPONDENCE DATA

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ATTORNEY DOCKET NUMBER: TIP-08-1382

NAME OF SUBMITTER: Leslie Hood

PATENT

REEL: 022033 FRAME: 0365

Total Attachments: 1

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PATENT REEL: 022033 FRAME: 0366

ASSIGNMENT

WHEREAS, we, Sadanori Kumazawa; Hiroyuki Ohme; Yuki Amano; and Takamasa Owaki, citizens of Japan, residing at c/o Nagoya Plant, Toray Industries, Inc., 9-1, Oe-cho, Minato-ku, Nagoya-shi, Aichi, 4558502, Japan, (hereinafter referred to as "the undersigned"), having made an invention entitled THERMOPLASTIC RESIN COMPOSITION AND MOLDED ARTICLE THEREOF identified as PCT/JP2007/062842 filed June 27, 2007, and identified in US Application No. 12/306,761 _______, (DLA Piper is authorized to insert the Serial No. when known),

WHEREAS, Toray Industries, Inc., with offices located at 1-1 Nihonbashi-Muromachi 2-chome, Chuo-ku, Tokyo, 1038666, Japan (hereinafter referred to as "the assignee"), is desirous of acquiring the entire right, title and interest in said invention, said US application and all letters patent issuing for said invention,

NOW, THEREFORE, in consideration of One Dollar (\$1.00) and of other good and valuable consideration, receipt of which is hereby acknowledged, the undersigned, intending to be legally bound, do hereby sell, assign and transfer to the assignee the entire right, title and interest, for the United States of America, its territories and possessions, and for all foreign countries, in said invention, including said US application, all divisions and continuations thereof, all rights to claim priority based thereon, all rights to file foreign applications on said invention, and all letters patent and reissues thereof, issuing for said invention in the United States of America and in any and all foreign countries.

It is agreed that the undersigned shall be legally bound, upon request of the assignee, or its successors or assigns or a legal representative thereof, to supply all information and evidence of which the undersigned has knowledge or possession, relating to the making and practice of said invention, to testify in any legal proceeding relating thereto, to execute all instruments proper to patent the invention in the United States of America and foreign countries in the name of the assignee, and to execute all instruments proper to carry out the intent of this instrument. If the undersigned includes more than one individual, these obligations shall apply to all of the undersigned both individually and collectively.

The rights and property herein conveyed by the undersigned are free and clear of any encumbrance.

EXECUTED on the date(s) set forth below.

Troposter 5,2008 2004 Date	<u>Aodanori Humanawo</u> Sadanori Kumazawa	
Accessor to 2007 Date	<u>Linas Ar Olase</u> Hiroyuki Ohme	***************************************
November 11,2008	<u>Yuki Amano</u> Yuki Amano	
November 19,2008 3 3	Takamasa Owala` Takamasa Owaki	
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PATENT REEL: 022033 FRAME: 0367

RECORDED: 12/29/2008